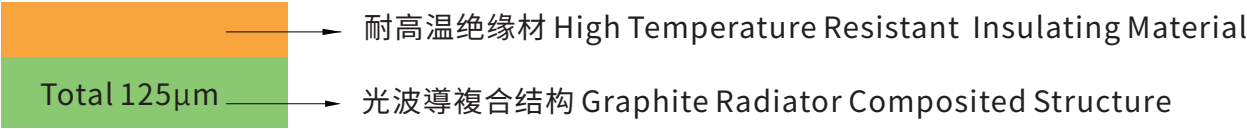


OWG-010J-CFZ

產品結構 Structure



性能參數 Technical Data

ITEM	Unit	Value
Substrate	Copper	
Sputtering	Graphite	
Peeling Strength	%	100
Elongation	%	> 1
Temperature	°C	-20~+200
Thermal Conductivity	W/m•K	>350
Thermal Emissivity	-	0.94
Flame Retardant	-	UL94 V-0
Width	mm	500/600
Thickness	μm	125

* The above product data is based on testing conducted in our laboratory and partial estimated data. It is provided for your reference only.

Features

- Possesses excellent flexibility and reworkability characteristics, and does not contain any organic materials, making it easy to recycle and meeting environmental requirements.
- The use of a single material provides both high resistance to EMI and uniform heat dissipation, allowing for material and thickness savings.
- The pure graphite sputtering coating processing is chip-resistant and fracture-resistant.
- Demonstrates superior axial heat conduction; the graphite layer and copper layer are vacuum-coated, eliminating interfacial thermal resistance.
- Material exhibits good density and adhesion, and offers far-infrared radiation heat dissipation effects.
- The copper layer features thermal buffering properties, enabling rapid heat transfer. Particularly suitable for high-efficiency/high-power IC applications requiring short-duration, instantaneous operation.

環保測試 Environmental

符合RoHS 與歐盟無鹵標準
RoHS compliant and EU halogen-free